TOSHIBA Field Effect Transistor Silicon P Channel MOS Type ( $L^2-\pi$ -MOSV)

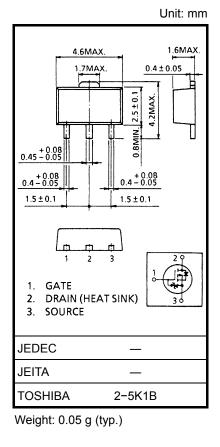
# 2SJ508

## Chopper Regulator, DC–DC Converter and Motor Drive Applications

- 4-V gate drive
- Low drain-source ON resistance  $R_{DS}(ON) = 1.34 \Omega$  (typ.)
- High forward transfer admittance  $\therefore$  |Y<sub>fs</sub>| = 0.7 S (typ.)
- Low leakage current  $: I_{DSS} = -100 \ \mu A(max) (V_{DS} = -100 \ V)$
- Enhancement mode :  $V_{th} = -0.8 \sim -2.0 V (V_{DS} = -10 V, I_D = -1 mA)$

#### Absolute Maximum Ratings (Ta = 25°C)

Characteristics		Symbol	Rating	Unit	
Drain-source voltage		V <sub>DSS</sub>	-100	V	
Drain-gate voltage (R <sub>GS</sub> = 20 kΩ)		V <sub>DGR</sub>	-100	V	
Gate-source voltage		V <sub>GSS</sub>	±20	V	
Drain current	DC (Note 1)	۱ <sub>D</sub>	-1	А	
	Pulse (Note 1)	I <sub>DP</sub>	-3	А	
Drain power dissipation	ו	PD	0.5	W	
Drain power dissipation (Note 2)		PD	1.5	W	
Single pulse avalanche energy (Note 3)		E <sub>AS</sub>	136.5	mJ	
Avalanche current		I <sub>AR</sub>	-1	А	
Repetitive avalanche e	nergy (Note 4)	E <sub>AR</sub>	0.05	mJ	
Channel temperature		T <sub>ch</sub>	150	°C	
Storage temperature range		T <sub>stg</sub>	-55~150	°C	



Note: Using continuously under heavy loads (e.g. the application of high temperature/current/voltage and the significant change in temperature, etc.) may cause this product to decrease in the reliability significantly even if the operating conditions (i.e. operating temperature/current/voltage, etc.) are within the absolute maximum ratings. Please design the appropriate reliability upon reviewing the Toshiba Semiconductor Reliability Handbook ("Handling Precautions"/Derating Concept and Methods) and individual reliability data (i.e. reliability test report and estimated failure rate, etc.).

#### **Thermal Characteristics**

Characteristics	Symbol	Max	Unit	
Thermal resistance, channel to ambient	R <sub>th (ch−a)</sub>	250	°C / W	

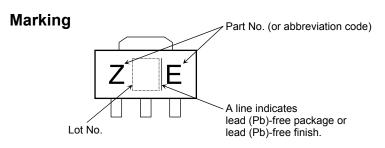
Note 1: Ensure that the channel temperature does not exceed 150°C.

Note 2: Mounted on a ceramic substrate (25.4 mm × 25.4 mm × 0.8 mm)

Note 3: V\_DD = –50 V, T\_ch = 25°C (initial), L = 168 mH, R\_G = 25  $\Omega,$  I\_AR = –1 A

Note 4: Repetitive rating: pulse width limited by maximum channel temperature

This transistor is an electrostatic-sensitive device. Please handle with caution.



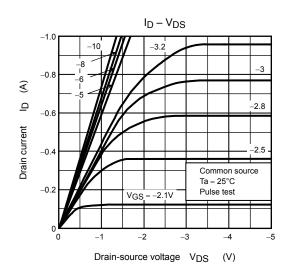
Electrical Characteristics (Ta = 25°C)

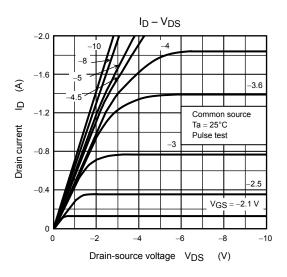
Charac	teristics	Symbol	Test Condition	Min	Тур.	Max	Unit	
Gate leakage cu	rrent	IGSS	V <sub>GS</sub> = ±16 V, V <sub>DS</sub> = 0 V		_	±10	μA	
Drain cut-off cu	rrent	IDSS	V <sub>DS</sub> = -100 V, V <sub>GS</sub> = 0 V	—	_	-100	μA	
Drain-source br voltage	eakdown	V (BR) DSS	I <sub>D</sub> = -10 mA, V <sub>GS</sub> = 0 V	-100	_	_	V	
Gate threshold v	oltage	V <sub>th</sub>	$V_{DS} = -10 \text{ V}, \text{ I}_{D} = -1 \text{ mA}$	-0.8	—	-2.0	V	
Drain-source ON resistance		R <sub>DS (ON)</sub>	$V_{GS}$ = -4 V, I <sub>D</sub> = -0.5 A	—	1.68	2.5	Ω	
			$V_{GS}$ = -10 V, I <sub>D</sub> = -0.5 A	_	1.34	1.9	12	
Forward transfer	admittance	Y <sub>fs</sub>	$V_{DS}$ = -10 V, I <sub>D</sub> = -0.5 A	0.3	0.7	_	S	
Input capacitance	e	C <sub>iss</sub>		_	135	_		
Reverse transfer capacitance		C <sub>rss</sub>	V <sub>DS</sub> = −10 V, V <sub>GS</sub> = 0 V, f = 1 MHz	_	22	—	pF	
Output capacitance		Coss		_	48	—		
Switching time	Rise time	tr	$V_{GS}_{-10V} \downarrow I_{D} = -0.5A$ $V_{OUT}$ $V_{UD} = -50V$ $V_{DD} = -50V$ $V_{UD} = 1\%, t_{W} = 10\mu s$	_	20	_		
	Turn-on time	t <sub>on</sub>		_	32	_	- ns	
	Fall time	t <sub>f</sub>		_	25	—		
	Turn-off time	t <sub>off</sub>		—	130	—		
Total gate charge (Gate-source plus gate-drain)		Qg	V <sub>DD</sub> ≈ −80 V, V <sub>GS</sub> = −10 V,	_	6.3	—	nC	
Gate-source charge		Q <sub>gs</sub>	$I_D = -1 A$	_	4.1	—		
Gate-drain ("miller") charge		Q <sub>gd</sub>		—	2.2	—		

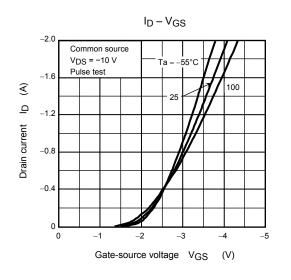
### Source–Drain Ratings and Characteristics (Ta = 25°C)

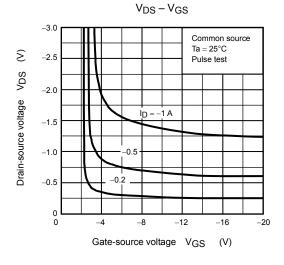
Characteristics	Symbol	Test Condition	Min	Тур.	Max	Unit
Continuous drain reverse current (Note 1)	I <sub>DR</sub>	_	_	_	-1	A
Pulse drain reverse current (Note 1)	I <sub>DRP</sub>	_	_	_	-3	А
Forward voltage (diode)	V <sub>DSF</sub>	I <sub>DR</sub> = -1 A, V <sub>GS</sub> = 0 V	_	_	1.5	V
Reverse recovery time	t <sub>rr</sub>	I <sub>DR</sub> = -1 A, V <sub>GS</sub> = 0 V	_	90	_	ns
Reverse recovery charge	Qrr	dI <sub>DR</sub> / dt = 50 A / μs		180		nC

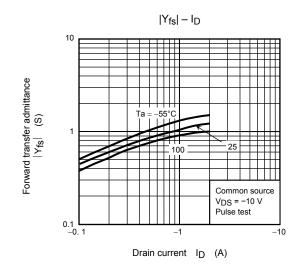
## **TOSHIBA**



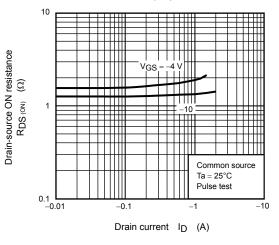




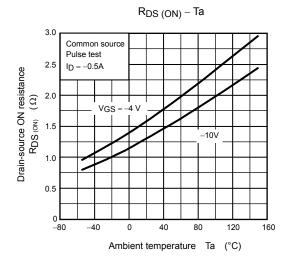


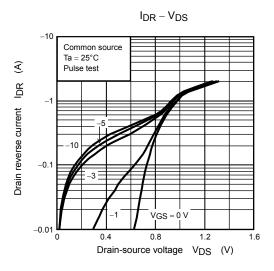


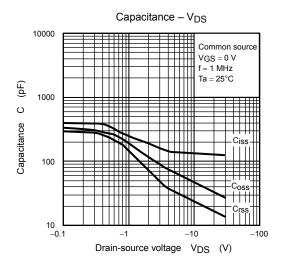
R<sub>DS (ON)</sub> – I<sub>D</sub>



## TOSHIBA







2.0

1.5

1.0

0.5

0 L 0

Drain power dissipation PD (W)

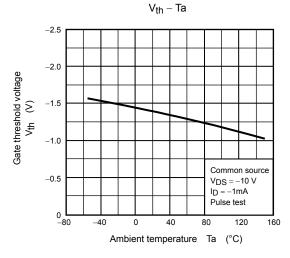
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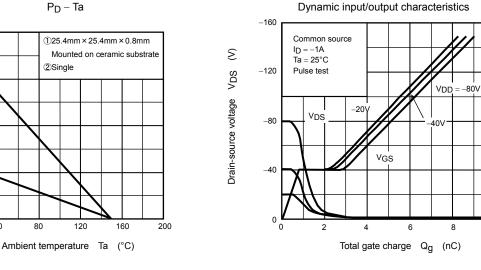
2

40

80

120







②Single

-16

-12

-8

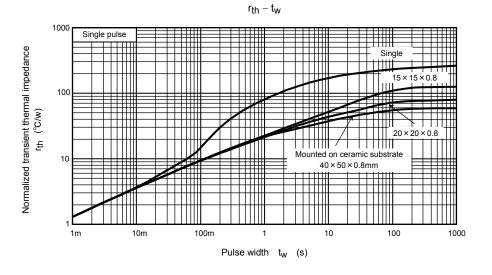
4

10<sup>0</sup>

8

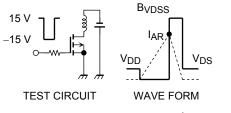
S

Gate-source voltage VGS



SAFE OPERATING AREA -10 ID max (pulsed) ID max (continuous) ìш Ð E10 ms ₽ Drain current -0.1 DC operation Ta = 25°C -0.01 : Single nonrepetitive pulse Tc = 25°C Curves must be derated VDSS max linearly with increase in -0. 001 -0.1 -1 -10 -100 -1000 Drain-source voltage VDS (V)

EAS - T<sub>ch</sub>



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